

Title (en)

DEVICE AND METHOD FOR MAKING DEVICES COMPRISING AT LEAST A CHIP MOUNTED ON A SUPPORT

Title (de)

VORRICHTUNG UND HERSTELLUNGSVERFAHREN MIT ZUMINDEST EINEM CHIP AUF EINEM TRÄGER

Title (fr)

DISPOSITIF ET PROCEDE DE FABRICATION DE DISPOSITIFS COMPRENANT AU MOINS UNE PUCE MONTEE SUR UN SUPPORT

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Application

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Abstract (en)

[origin: WO0077731A1] The invention concerns a method for making a device comprising a support (2) associated with at least a microcircuit in the form of a chip (6), for example a chip card. The invention is characterised in that it comprises, for the or each chip, steps which consist in: first providing for said chip an assembly consisting of a thin chip (6) maintained by a first surface (6b) integral with a substrate (8) and having on an opposite second surface (6a) at least a bond pad (12); forming, on a surface (2a) of the support a communication interface (4) comprising at least a connecting element (4b) with said chip; then, successively: placing said assembly comprising the chip (6) and the substrate (8) against the communication interface, with at least a bond pad (12) of the chip positioned against a corresponding connection element (4b; 24a, 24b) of the communication interface; integrating the or each pad with its respective connection element; and removing said substrate (8) from said first surface (6b) of the chip. The method advantageously uses the SOI chip technology.

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